

1-31-92



DEPARTMENT OF COMMERCE Patent and Trademark Office

Docket No.: 6161.0568.US

103040570 To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

	1. Name of conveying party(ies):	2. Name and address of receiving party(ies):
,	Keun-Ho JANG, Hyun-Gue KIM, and Hong-Ro LEE	Name: Samsung SDI Co., Ltd.
>	Additional names of conveying party(ies) attached? ☐ yes ☐ no	Internal Address: Street Address: 575, Shin-dong, Yeongtong-gu,
	3. Nature of Conveyance	City: Suwon-si, Gyeonggi-do State or Country: The Republic of KOREA
	Security Agreement Change of Name Other	Additional name(s) & address(es) attached? ☐ yes ☐ no
	Execution Date: June 30, 2005 4. Application number(s) or patent number(s):	
	TITLE: METHOD OF MANUFACTURING THIN FILM SILICON LAYER, THIN FILM TRANSISTOR MANUFACTURING THE THIN FILM TRANSISTOR DISPLAY COMPRISING THE THIN FILM TRANSISTOR	ACTURED USING THE METHOD AND FLAT PANEL
	If this document is being filed together with a new application,	, the execution date of the application is
	A. Patent Application No(s). 11/116,276	
	B. Patent No(s). Additional numbers attach	ned? 🗌 Yes 🛛 No
	5. Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved: 1
	Hae-Chan Park	7. Total fee (37 CFR 3.41): \$40.00
	McGuireWoods LLP 1750 Tysons Boulevard, Suite 1800	⊠ Enclosed
	McLean, Virginia 22102	 ✓ Authorized to be charged to deposit account ✓ Total fee due ✓ Any deficiencies in the enclosed fees
		8. Deposit account number: 23-1951
	9. Statement and signature	<u> </u>
	To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.	
	Hae-Chan Park, Reg. No. 50,114 Reg. No. 50,114	ache, leg. N. 48,342 July 8, 2005
	Name of Person Signing Signatur	Date

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ASSIGNMENT

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in

an application for United States Letters Patent entitled

METHOD OF MANUFACTURING THIN FILM TRANSISTOR HAVING POLYCRYSTALLINE SILICON LAYER, THIN FILM TRANSISTOR MANUFACTURED USING THE METHOD AND FLAT PANEL DISPLAY COMPRISING THE THIN FILM TRANSISTOR

("Applic	cation");		
	upon which United States Letters Patent, Patent Number ("Patent");	, has issued	

Whereas, Assignor desires to convey all rights, title and interests in and to the same to Samsung SDI Co., Ltd. ("Assignee"), with offices located at 575 Shin-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, The Republic of KOREA;

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States, , any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the U.S. or any and all foreign countries and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.

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IN WITNESS WHEREOF, Assignor has hereunto set hand and seal.

Assignor:	
Signature:	Jay
Print Name:	Keun-Ho Jang
Address:	c/o Samsung SDI Co., Ltd., 575 Shin-dong, Yeongtong-qu, Suwon-si, Gyeongqi-do
	REPUBLIC OF KOREA
Date:	30 JUNE 2005
Assignor: Signature:	73 对于
Print	Hyun-Gue Kim
	o/o Samsung SDI Co., Ltd., 575 Shin-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do
Date:	30 JUNE 2005
Assignor: Signature:	6)~~
Print Name:	Hong-Ro Lee
	c/o Samsung SDI Co., Ltd., 575 Shin-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do
Date:	30 JUNE 2005

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RECORDED: 07/08/2005